

<u>3SK239A</u>

Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DS}	12	V
Gate 1 to source voltage	V _{G1S}	-6	V
Gate 2 to source voltage	V _{G2S}	-6	V
Drain current	I _D	50	mA
Channel power dissipation	Pch	100	mW
Channel temperature	Tch	125	°C
Storage temperature	Tstg	–55 to +125	°C

Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source leakage current	I _{DSX}	—	_	50	μA	$V_{\text{DS}} = 12 \text{ V}, V_{\text{G1S}} = -3 \text{ V},$ $V_{\text{G2S}} = 0$
Gate 1 to source breakdown voltage	$V_{(\text{BR})\text{G1SS}}$	-6	_	_	V	$I_{G1} = -10 \ \mu A, \ V_{G2S} = V_{DS} = 0$
Gate 2 to source breakdown voltage	$V_{(BR)G2SS}$	-6	_	_	V	$I_{G2} = -10 \ \mu A, \ V_{G1S} = V_{DS} = 0$
Gate 1 leakage current	I _{G1SS}	_	_	-5	μA	$V_{G1S} = -5 V, V_{G2S} = V_{DS} = 0$
Gate 2 leakage current	I _{G2SS}	—	—	-5	μA	$V_{G2S} = -5 V, V_{G1S} = V_{DS} = 0$
Drain current	I _{DSS}	14	19	28	mA	V_{DS} = 5 V, V_{G1S} = V_{G2S} = 0
Gate 1 to source cutoff voltage	$V_{\text{G1S(off)}}$	—	-1.2	-1.6	V	$V_{DS} = 5 V, V_{G2S} = 0,$ $I_{D} = 100 \ \mu A$
Gate 2 to source cutoff voltage	$V_{\text{G2S(off)}}$	_	-1.2	-1.6	V	$V_{DS} = 5 V, V_{G1S} = 0,$ $I_{D} = 100 \ \mu A$
Forward transfer admittance	$ \mathbf{y}_{\mathrm{fs}} $	20	31	_	mS	$V_{DS} = 5 V, V_{G2S} = 1 V,$ $I_{D} = 10 mA, f = 1 kHz$
Input capacitance	Ciss	_	0.58	1.0	pF	V_{DS} = 5 V, V_{G1S} = V_{G2S} = -3 V, f = 1 MHz
Output capacitance	Coss	_	0.36	0.6	pF	
Reverse transfer capacitance	Crss	_	0.028	0.05	pF	
Power gain	PG	17	19	—	dB	$V_{DS} = 5 V, V_{G2S} = 1 V,$ $I_{D} = 10 mA, f = 900 MHz$
Noise figure	NF	_	1.3	2.0	dB	

Note: Marking is "XR-".

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